Session Program

24–27 Apr 2018

AIDA-2020 Third Annual Meeting

WP4 Micro-electronics and interconnections

Centro San Domenico
Centro San Domenico Piazza S. Domenico, 13, 40124 Bologna BO, Italy

Thursday 26 April

09:00

WP4 Micro-electronics and interconnections: Micro-electronics and interconnections

Session | **Location:** Salone Bolognini | **Conveners:** Valerio Re, Christophe De La Taille, Valerio Re

09:00–09:05 Introduction

Speakers

Christophe De La Taille, Valerio Re

Location

Salone Bolognini

09:05–09:20 TSV developments at UBonn

Speakers

Fabian Huegging, Fabian Huegging

Location

Salone Bolognini

09:20–09:35 TSV developments in Glasgow

Speakers

Richard Bates, Richard Bates

Location

Salone Bolognini

09:35–09:50 TSV developments at Uppsala

Speaker

Richard Brenner

Location

Salone Bolognini

09:50–10:00

discussion and plans for TSV fabrication in 65 nm CMOS wafers from the RD53 run

Location

Salone Bolognini

10:00–10:30 Coffee Break

10:30–11:00 Test results on the RD53A chip and future plans

Speakers

Francesco De Canio, Francesco De Canio, Luigi Gaioni

Location

Salone Bolognini

11:00–11:15 Update on 65nm developments in Bonn

Speaker

Hans Krueger

Location

Salone Bolognini

11:15–11:30 **The CHIPIX65 demonstrator chip**

Speakers
Ennio Monteil, Lino Demaria

Location
Salone Bolognini

11:30–11:45 **TSMC 130 nm developments at OMEGA and Desy/Heidelberg**

Speakers
Ludovic Raux, Nathalie Seguin-Moreau

Location
Salone Bolognini

11:45–12:00 **developments at AGH Krakow**

Speaker
Marek Idzik

Location
Salone Bolognini

12:00–12:15 **A high precision TDC for CMS MG-RPC in TSMC 130 nm**

Speaker
Mokrane DAHOUMANE

Location
Salone Bolognini

12:15–12:30 **Discussion**

Location
Salone Bolognini

12:30